

# SHINDENGEN

## HVX-2 Series Power MOSFET

N-Channel Enhancement type

**2SK2665  
( F3S90HVX2 )**

**900V 3A**

### FEATURES

- Input capacitance ( $C_{iss}$ ) is small.  
Especially, input capacitance at 0 bias is small.
- The static  $R_{ds(on)}$  is small.
- The switching time is fast.
- Avalanche resistance guaranteed.

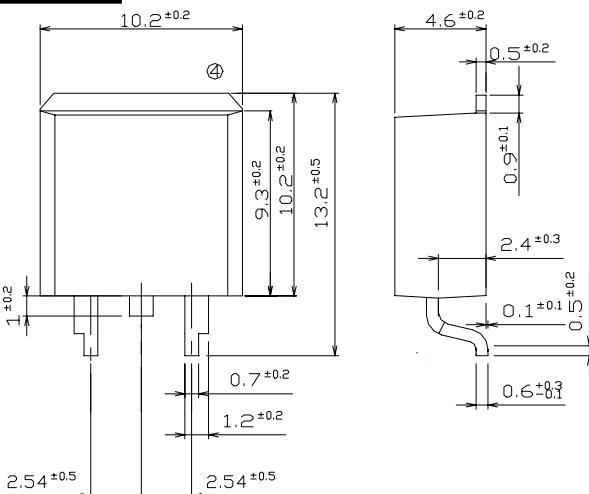
### APPLICATION

- Switching power supply of AC 240V input
- High voltage power supply
- Inverter

### OUTLINE DIMENSIONS

Case : STO-220

(Unit : mm)



Ⓐ Ⓑ Ⓒ Ⓓ

Ⓐ : G

Ⓑ : D

Ⓒ : S

Ⓓ : D

### RATINGS

#### ● Absolute Maximum Ratings ( $T_c = 25^\circ\text{C}$ )

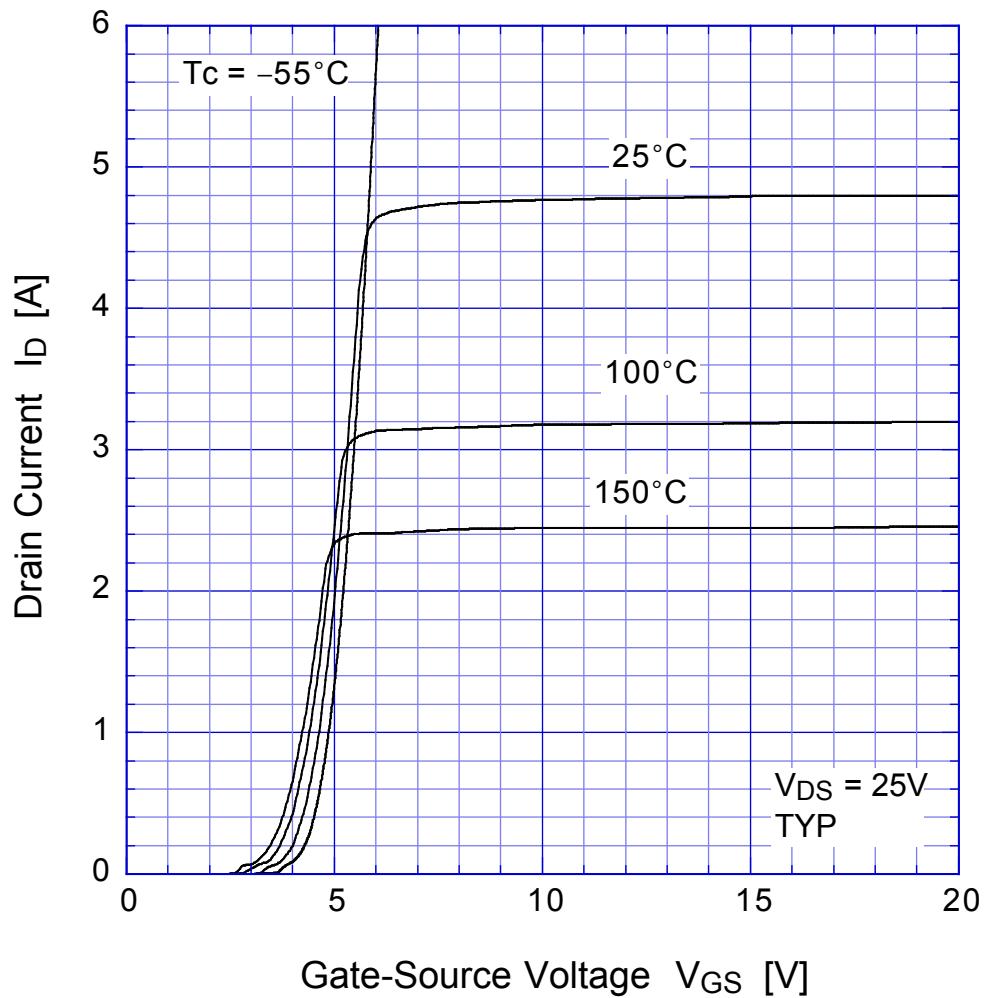
Item	Symbol	Conditions	Ratings	Unit
Storage Temperature	$T_{stg}$		-55~150	$^\circ\text{C}$
Channel Temperature	$T_{ch}$		150	
Drain-Source Voltage	$V_{DSS}$		900	V
Gate-Source Voltage	$V_{GSS}$		$\pm 30$	
Continuous Drain Current(DC)	$I_D$		3	A
Continuous Drain Current(Peak)	$I_{DP}$	Pulse width $\leq 10 \mu\text{ s}$ , Duty cycle $\leq 1/100$	6	
Continuous Source Current(DC)	$I_S$		3	
Total Power Dissipation	$P_T$		50	W
Repetitive Avalanche Current	$I_{AR}$	$T_{ch} = 150^\circ\text{C}$	3	A
Single Avalanche Energy	$E_{AS}$	$T_{ch} = 25^\circ\text{C}$	48	mJ
Repetitive Avalanche Energy	$E_{AR}$	$T_{ch} = 25^\circ\text{C}$	4.8	

●Electrical Characteristics T<sub>c</sub> = 25°C

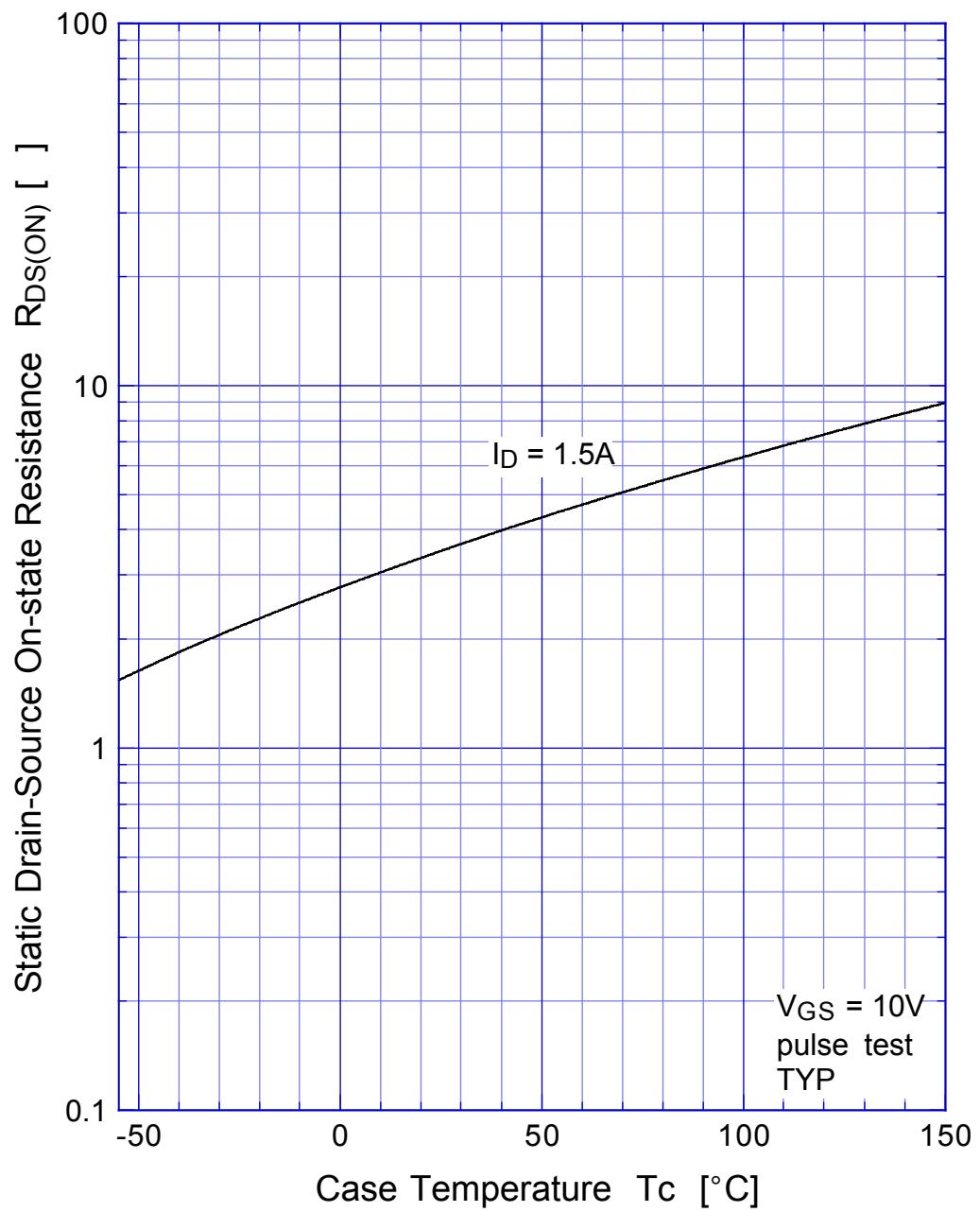
Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	ID = 1mA, V <sub>GS</sub> = 0V	900			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 900V, V <sub>GS</sub> = 0V			250	μA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±30V, V <sub>DS</sub> = 0V			±0.1	
Forward Transconductance	g <sub>fs</sub>	ID = 1.5A, V <sub>DS</sub> = 10V	1.5	2.5		S
Static Drain-Source On-state Resistance	R <sub>DSON</sub>	ID = 1.5A, V <sub>GS</sub> = 10V		3.5	4.7	Ω
Gate Threshold Voltage	V <sub>TH</sub>	ID = 1mA, V <sub>DS</sub> = 10V	2.5	3.0	3.5	V
Source-Drain Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 1.5A, V <sub>GS</sub> = 0V			1.5	
Thermal Resistance	θ <sub>jc</sub>	junction to case			2.5	°C/W
Total Gate Charge	Q <sub>g</sub>	V <sub>DD</sub> = 400V, V <sub>GS</sub> = 10V, I <sub>D</sub> = 3A		30		nC
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1MHz		630		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			16		
Output Capacitance	C <sub>oss</sub>			67		
Turn-On Time	t <sub>on</sub>	ID = 1.5A, V <sub>DD</sub> = 150V, R <sub>L</sub> = 100Ω		40	70	ns
Turn-Off Time	t <sub>off</sub>			140	230	

# 2SK2665

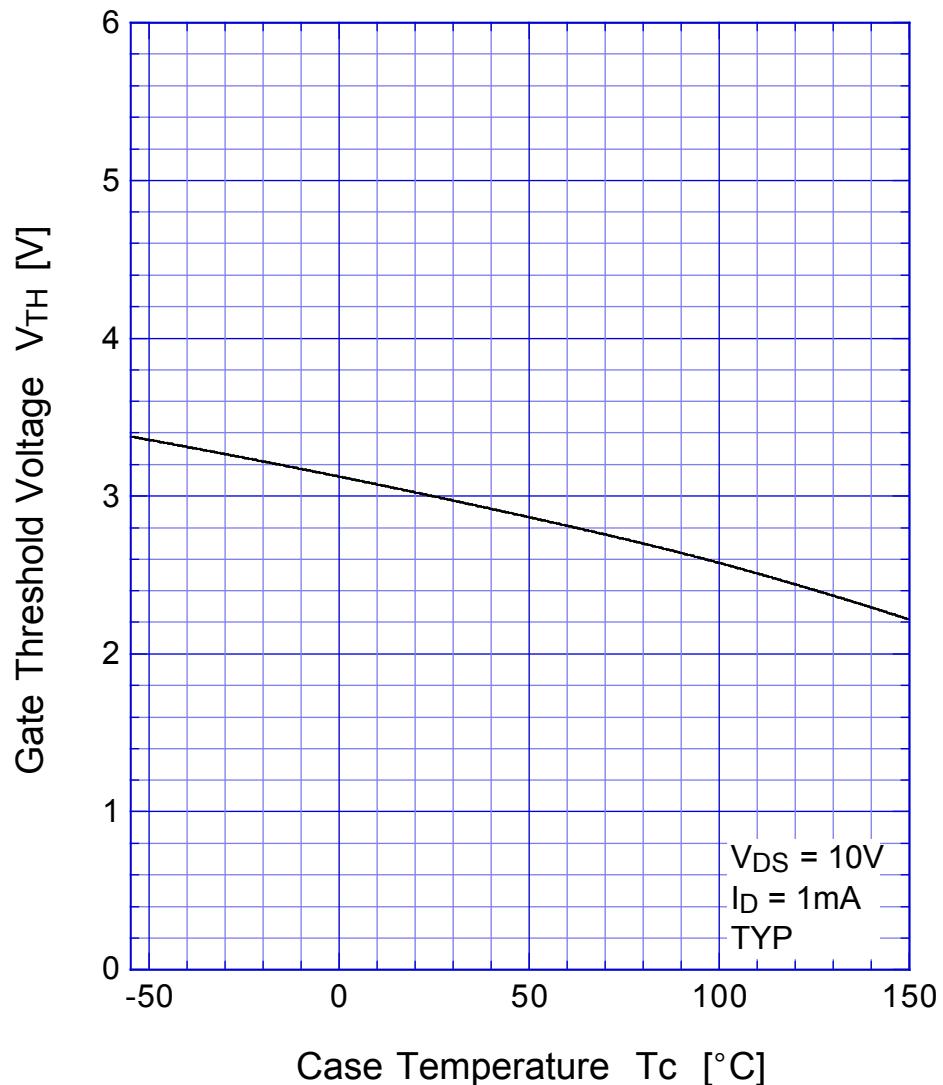
## Transfer Characteristics



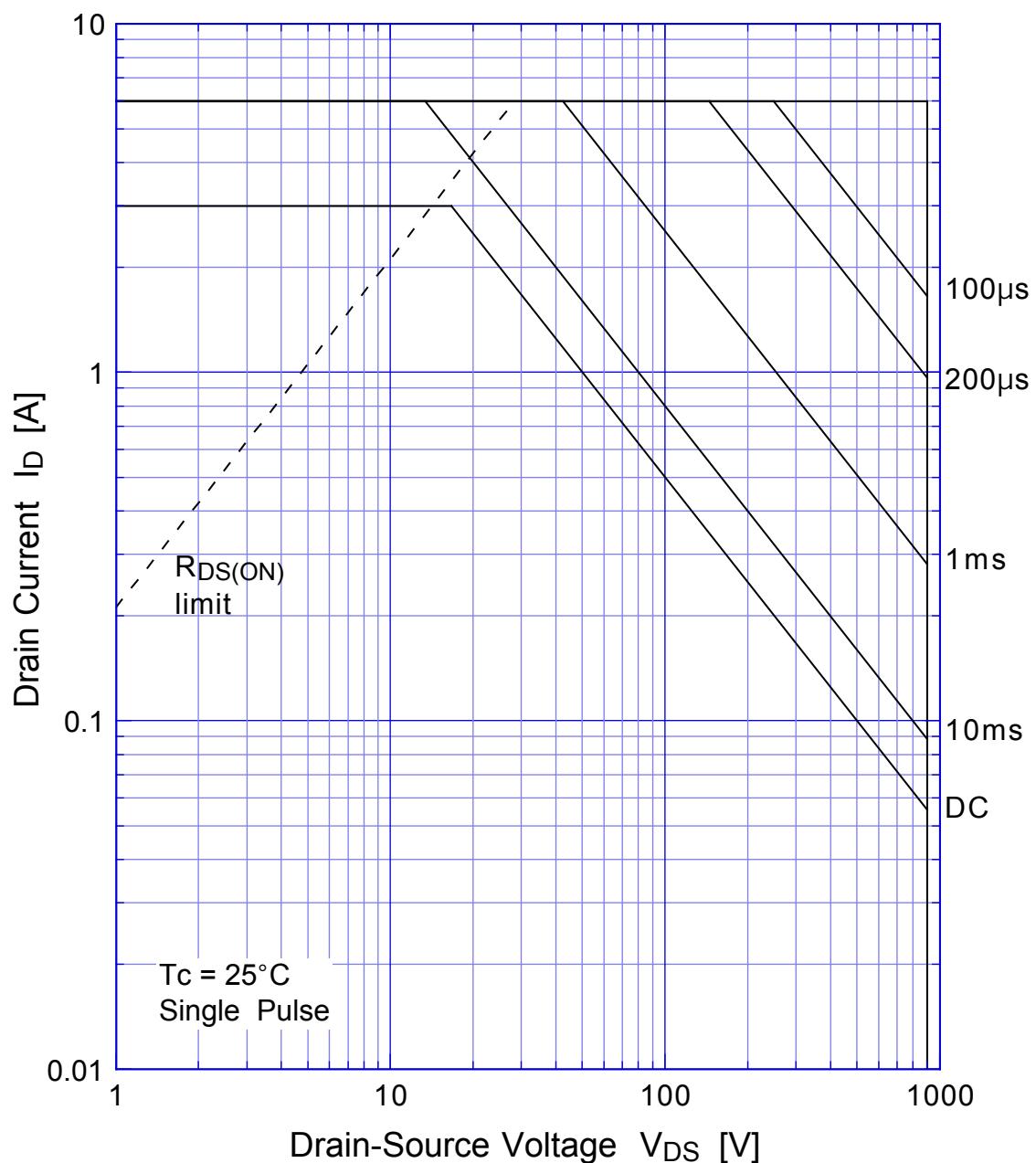
## **2SK2665 Static Drain-Source On-state Resistance**



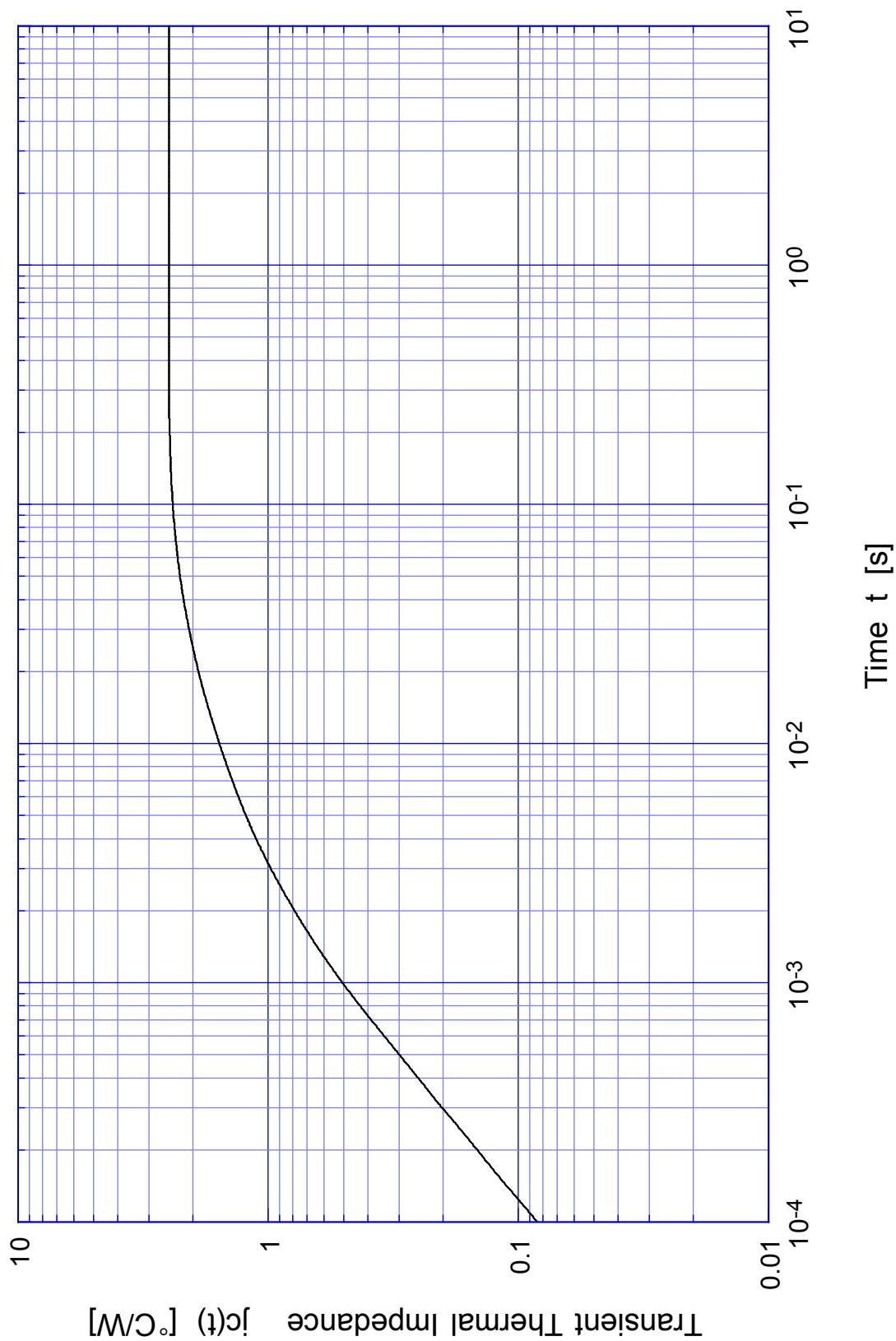
## 2SK2665 Gate Threshold Voltage



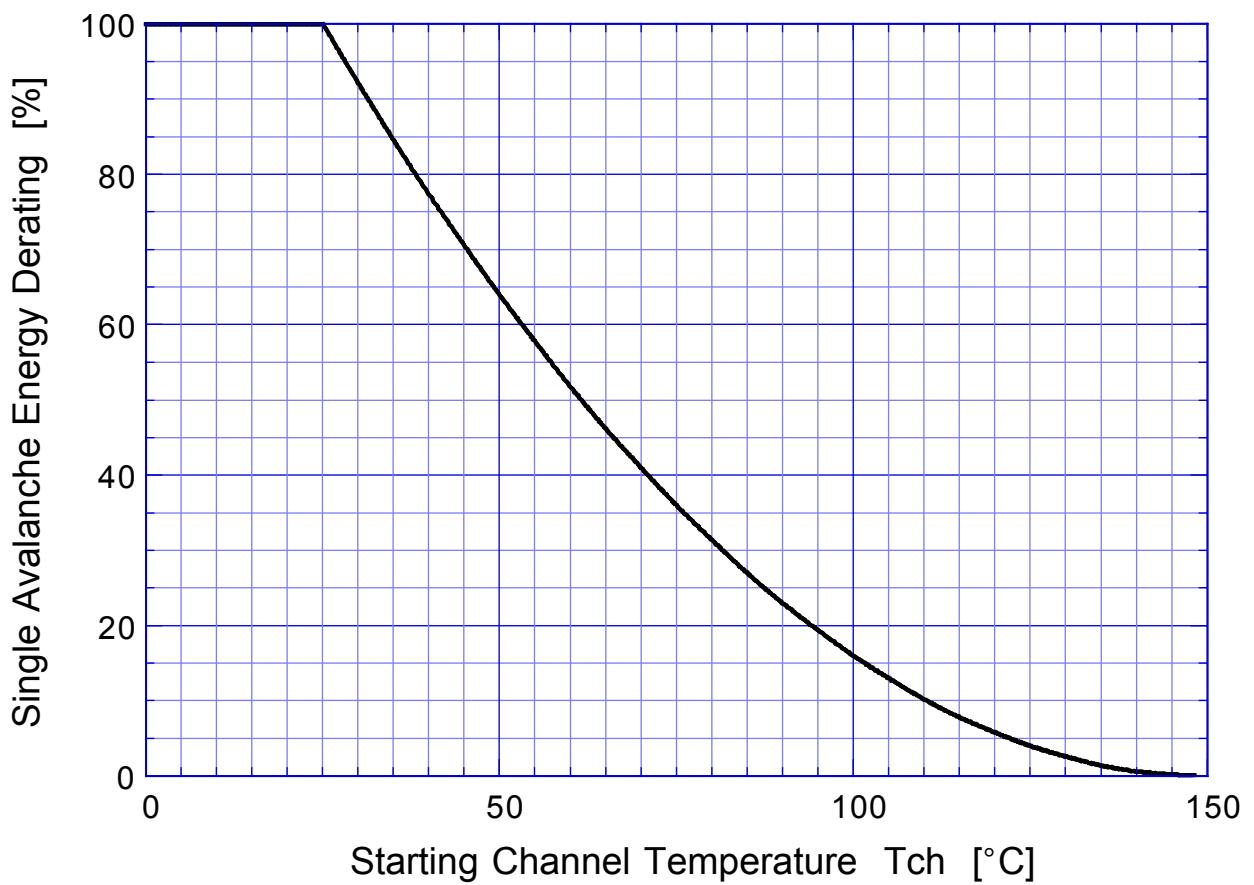
## 2SK2665 Safe Operating Area



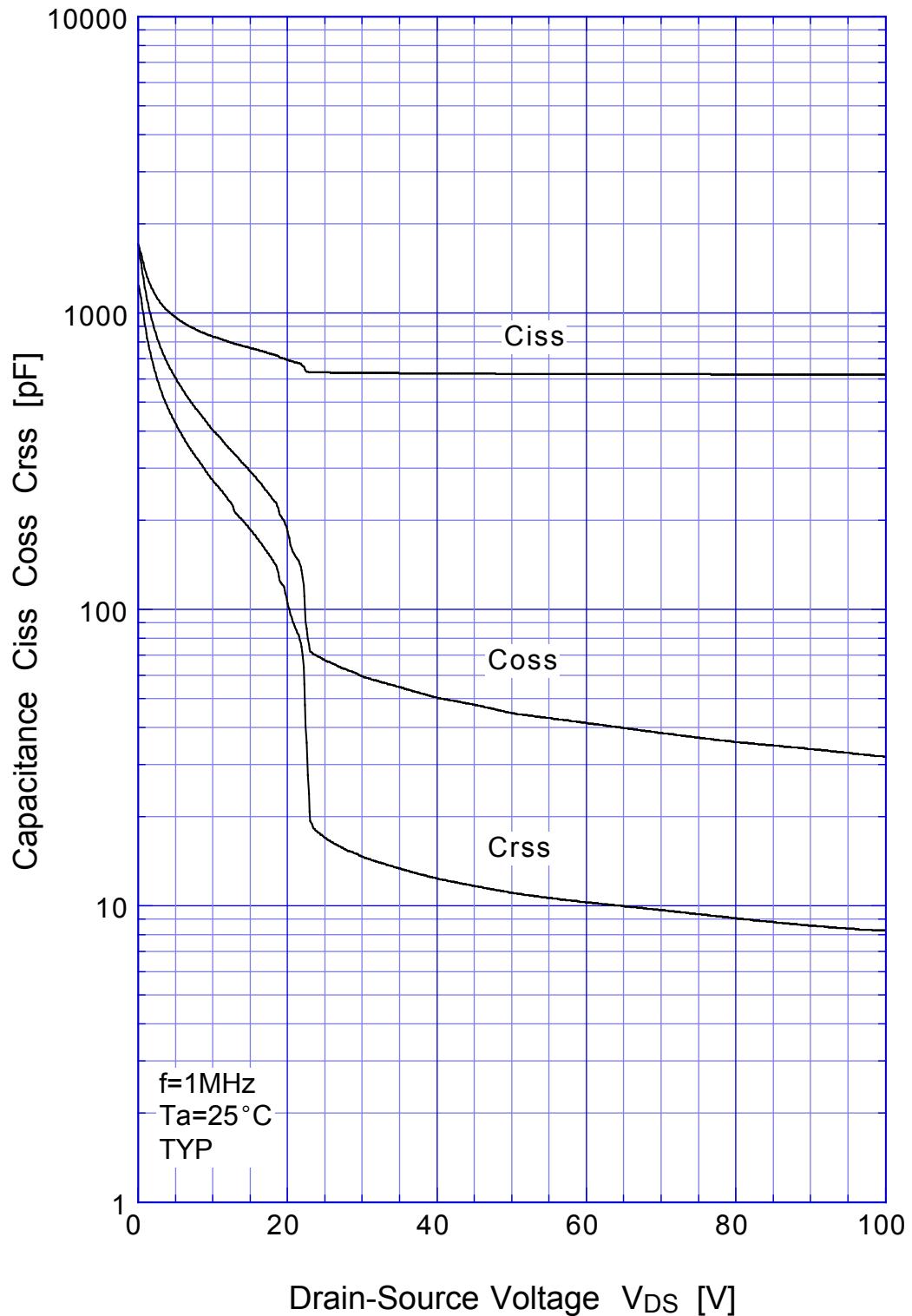
## 2SK2665 Transient Thermal Impedance



## **2SK2665 Single Avalanche Energy Derating**

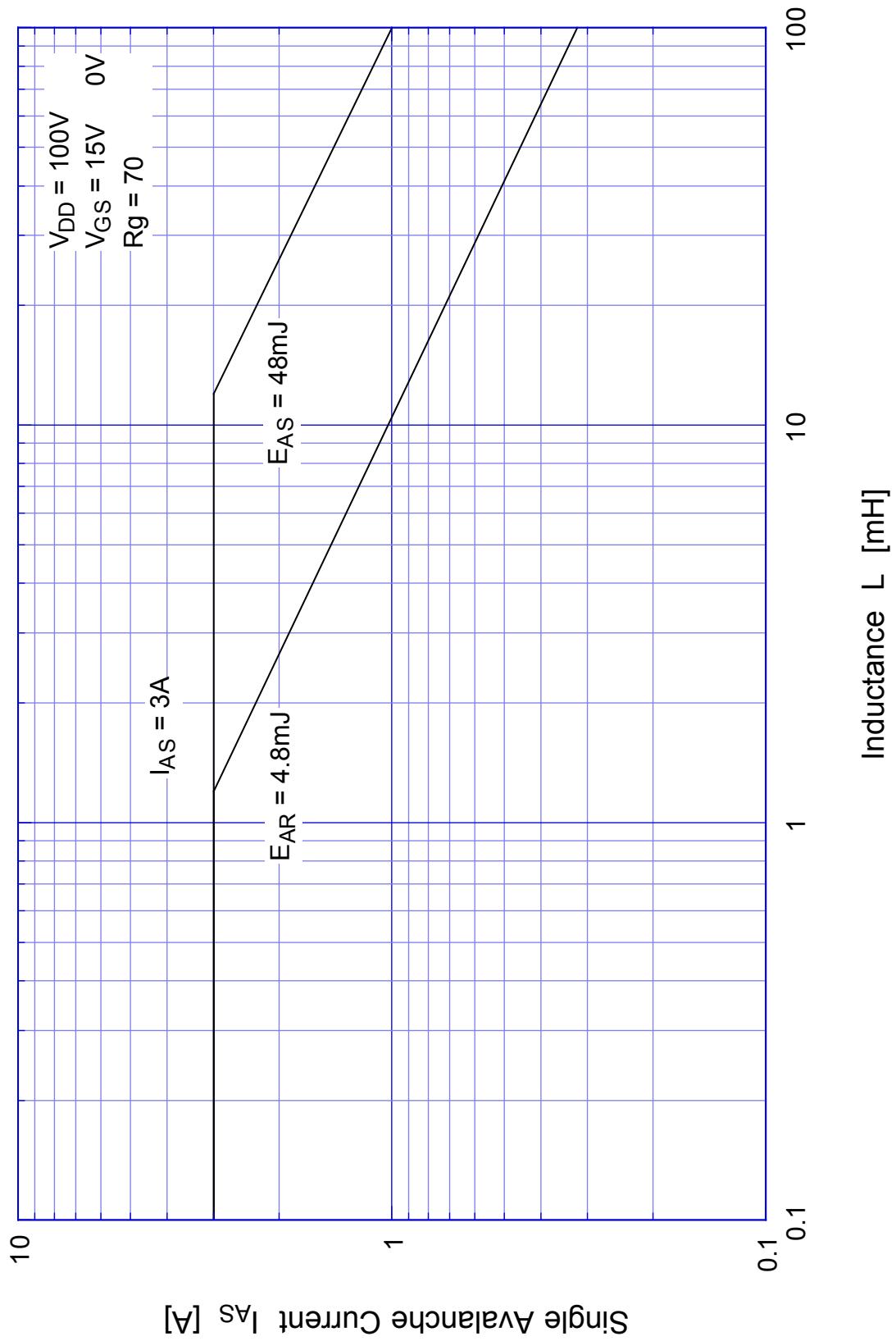


2SK2665 Capacitance



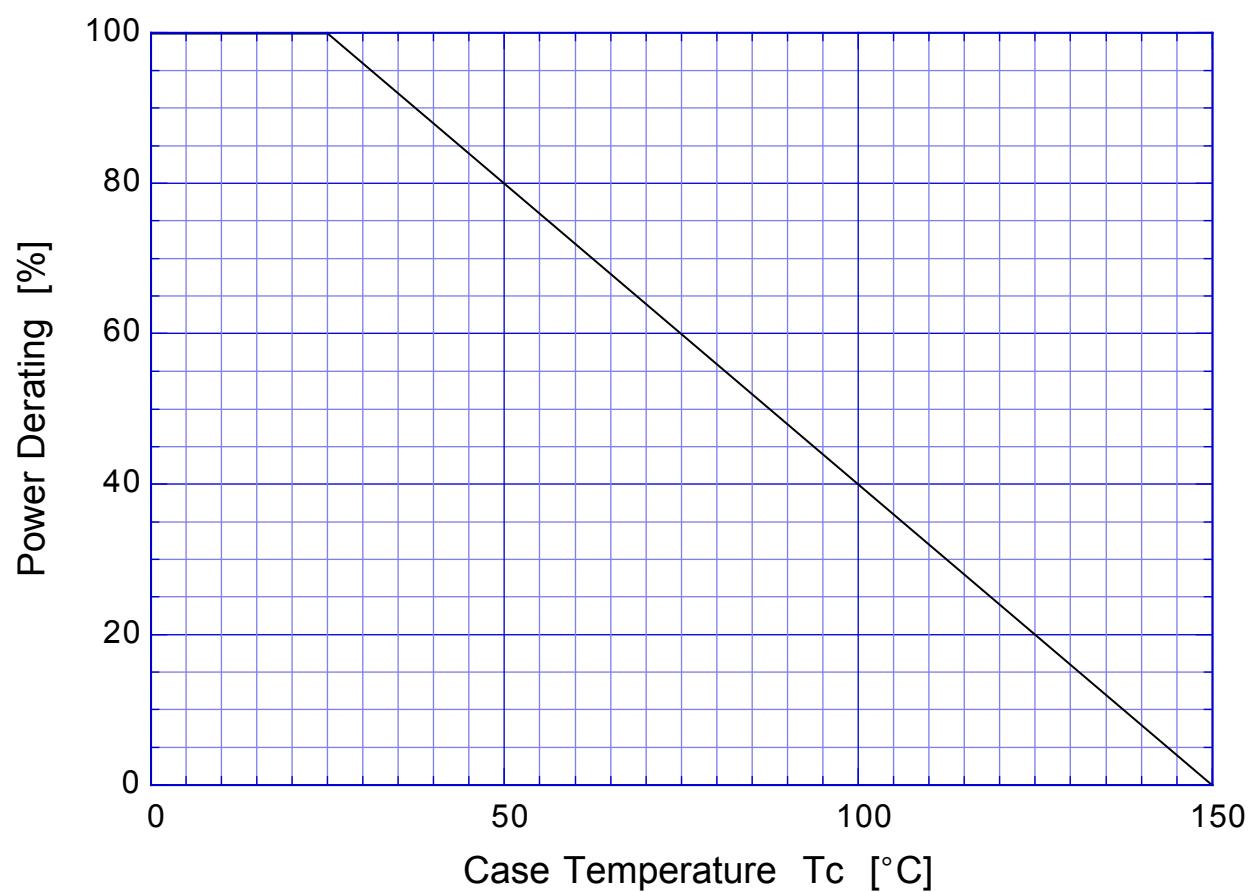
## 2SK2665 Single Avalanche Current - Inductive Load

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**2SK2665**

Power Derating



## 2SK2665

### Gate Charge Characteristics

